



Material Content Data Sheet



Sales Product Name	BTS50070-1EGA			Issued		29. August 2013		
MA#	MA001080470							
Package	PG-DSO-12-16			Weight*		397.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.100	1.78	1.78	17844	17844
leadframe	non noble metal	iron	7439-89-6	0.230	0.06		579	
	inorganic material	phosphorus	7723-14-0	0.069	0.02		174	
	non noble metal	copper	7440-50-8	230.106	57.82	57.90	578326	579079
wire	noble metal	gold	7440-57-5	0.224	0.06		564	
	non noble metal	aluminium	7429-90-5	0.859	0.22	0.28	2158	2722
encapsulation	organic material	carbon black	1333-86-4	0.297	0.07		747	
	plastics	epoxy resin	-	21.246	5.34		53398	
	inorganic material	silicondioxide	60676-86-0	127.032	31.93	37.34	319268	373413
leadfinish	non noble metal	tin	7440-31-5	4.235	1.06	1.06	10644	10644
plating	noble metal	silver	7440-22-4	2.172	0.55	0.55	5459	5459
glue	plastics	Polyimide	26023-21-2	0.205	0.05	0.05	514	514
solder	noble metal	silver	7440-22-4	0.103	0.03		258	
	non noble metal	tin	7440-31-5	0.082	0.02		207	
	non noble metal	lead	7439-92-1	3.923	0.99	1.04	9860	10325
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com